Your Trusted Service Partner

Performance You Can Rely On

Die - Wafer - Package - Module

Wafer Burn-in & Testing
Multi-temp & Custom Probe Support
25°C, 85°C, and 120°C.

Burn-In
Scalable Capacity With 1B+ devices
Tested Annually in 500+ chambers

System-Level Test
AI, Automotive, Data Servers,
Aerospace, Defense

Final Test
Seamless Test Conversion for Faster
Market Readiness

Industries We Serve

Automotive • Artificial Intelligence • Data Centers
• Aerospace & Defense
• High-Performance Computing

DEFENSE LOGISTICS AGENCY

SIRIM QAS INTERNATIONAL

BUREAU VERITAS 1828

ISO

STANDARDS MALAYSIA ACCREDITED